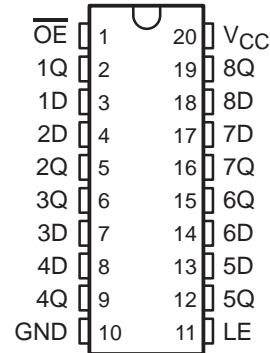


# SN54HCT373, SN74HCT373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCLS009D – MARCH 1984 – REVISED AUGUST 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State True Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 21$  ns
- $\pm 6$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Inputs Are TTL-Voltage Compatible
- Eight High-Current Latches in a Single Package
- Full Parallel Access for Loading

SN54HCT373 . . . J OR W PACKAGE  
SN74HCT373 . . . DB, DW, N, NS, OR PW PACKAGE  
(TOP VIEW)

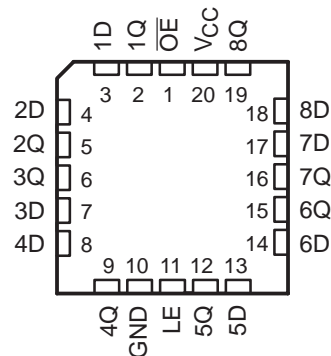


## description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'HCT373 devices are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

SN54HCT373 . . . FK PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74HCT373N	SN74HCT373N
	SOIC – DW	Tube of 25	SN74HCT373DW	HCT373
		Reel of 2000	SN74HCT373DWR	
	SOP – NS	Reel of 2000	SN74HCT373NSR	HCT373
	SSOP – DB	Reel of 2000	SN74HCT373DBR	HT373
	TSSOP – PW	Tube of 70	SN74HCT373PW	HT373
Reel of 2000		SN74HCT373PWR		
Reel of 250		SN74HCT373PWT		
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54HCT373J	SNJ54HCT373J
	CFP – W	Tube of 85	SNJ54HCT373W	SNJ54HCT373W
	LCCC – FK	Tube of 55	SNJ54HCT373FK	SNJ54HCT373FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54HCT373, SN74HCT373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCLS009D – MARCH 1984 – REVISED AUGUST 2003

## description/ordering information (continued)

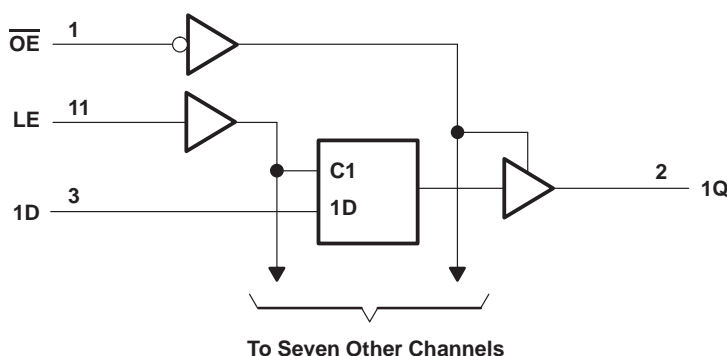
An output-enable ( $\overline{OE}$ ) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$  does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

FUNCTION TABLE  
(each latch)

INPUTS			OUTPUT
$\overline{OE}$	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	$Q_0$
H	X	X	Z

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous current through $V_{CC}$ or GND	±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54HCT373, SN74HCT373 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 3)

		SN54HCT373			SN74HCT373			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		2	2			V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		0.8			0.8	V
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	0		V <sub>CC</sub>	V
Δt/Δv	Input transition rise/fall time	500			500			ns
T <sub>A</sub>	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HCT373		SN74HCT373		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	4.5 V	I <sub>OH</sub> = -20 μA		4.4	4.499	4.4	4.4	V	
			I <sub>OH</sub> = -6 mA		3.98	4.3	3.7	3.84		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	4.5 V	I <sub>OL</sub> = 20 μA		0.001		0.1	0.1	V	
			I <sub>OL</sub> = 6 mA		0.17	0.26	0.4	0.33		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	5.5 V	±0.1	±100	±1000		±1000		nA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0	5.5 V	±0.01	±0.5	±10		±5		μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	5.5 V	8		160		80		μA	
ΔI <sub>CC</sub> <sup>†</sup>	One input at 0.5 V or 2.4 V, Other inputs at 0 or V <sub>CC</sub>	5.5 V	1.4	2.4	3		2.9		mA	
C <sub>i</sub>		4.5 V to 5.5 V	3	10	10		10		pF	

<sup>†</sup> This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V <sub>CC</sub>	T <sub>A</sub> = 25°C		SN54HCT373		SN74HCT373		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration, LE high	4.5 V	20		30		25		ns
		5.5 V	17		27		23		
t <sub>su</sub>	Setup time, data before LE↓	4.5 V	10		15		13		ns
		5.5 V	9		14		12		
t <sub>h</sub>	Hold time, data after LE↓	4.5 V	10		10		10		ns
		5.5 V	10		10		10		



**SN54HCT373, SN74HCT373**  
**OCTAL TRANSPARENT D-TYPE LATCHES**  
**WITH 3-STATE OUTPUTS**

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HCT373		SN74HCT373		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	D	Q	4.5 V	25	35	53	44	ns			
			5.5 V	21	32	48	40				
	LE	Any Q	4.5 V	28	35	53	44				
			5.5 V	25	32	48	40				
$t_{en}$	$\overline{OE}$	Any Q	4.5 V	26	35	53	44	ns			
			5.5 V	23	32	48	40				
$t_{dis}$	$\overline{OE}$	Any Q	4.5 V	23	35	53	44	ns			
			5.5 V	22	32	48	40				
$t_t$		Any Q	4.5 V	10	12	18	15	ns			
			5.5 V	9	11	16	14				

switching characteristics over recommended operating free-air temperature range,  $C_L = 150 \text{ pF}$  (unless otherwise noted) (see Figure 1)

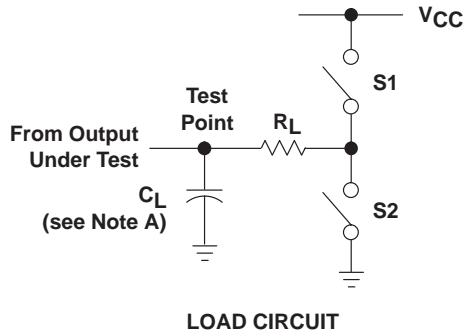
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HCT373		SN74HCT373		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	D	Q	4.5 V	32	52	79	65	ns			
			5.5 V	27	47	71	59				
	LE	Any Q	4.5 V	38	52	79	65				
			5.5 V	36	47	71	59				
$t_{en}$	$\overline{OE}$	Any Q	4.5 V	33	52	79	65	ns			
			5.5 V	28	47	71	59				
$t_t$		Any Q	4.5 V	18	42	63	53	ns			
			5.5 V	16	38	57	48				

operating characteristics,  $T_A = 25^\circ\text{C}$

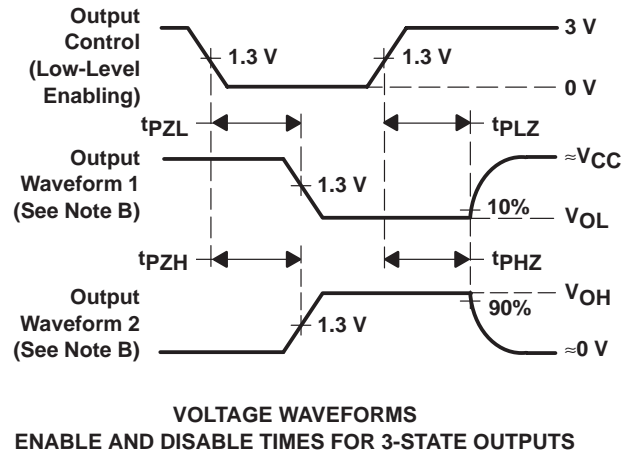
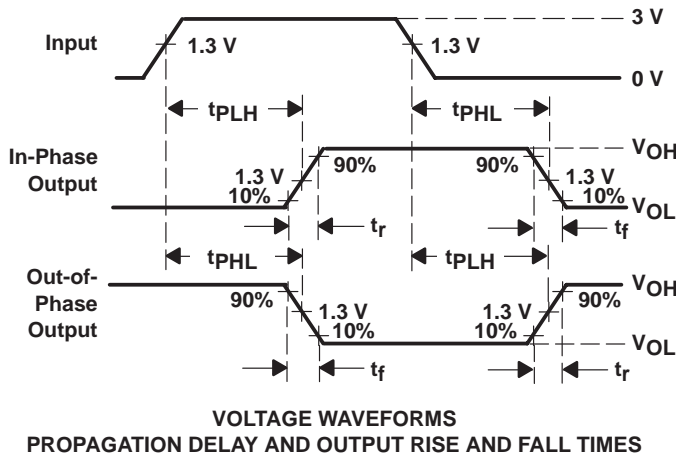
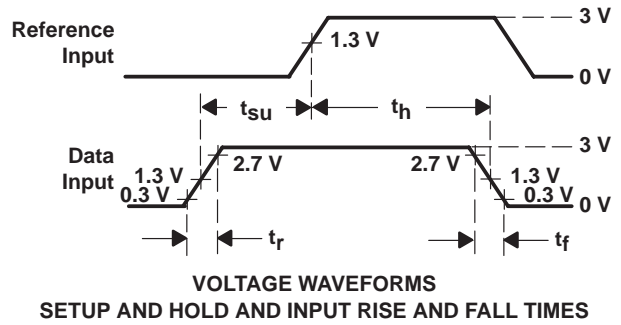
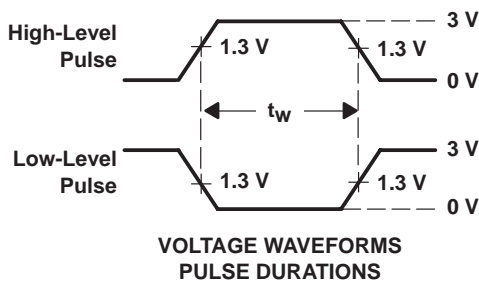
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per latch	No load	50	pF



PARAMETER MEASUREMENT INFORMATION



PARAMETER	$R_L$	$C_L$	S1	S2
$t_{en}$	1 k $\Omega$	50 pF or 150 pF	Open	Closed
			Closed	Open
$t_{dis}$	1 k $\Omega$	50 pF	Open	Closed
			Closed	Open
$t_{pd}$ or $t_t$	—	50 pF or 150 pF	Open	Open



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.  
 D. The outputs are measured one at a time with one input transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-86867012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-8686701RA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Call TI	
5962-8686701VRA	ACTIVE	CDIP	J	20	20	TBD	A42	N / A for Pkg Type	
5962-8686701VSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
JM38510/65453BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
JM38510/65453BSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
M38510/65453BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
M38510/65453BSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	
SN54HCT373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SN74HCT373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HCT373N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	
SN74HCT373NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HCT373NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74HCT373PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	
SN74HCT373PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HCT373PWTG4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54HCT373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54HCT373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	
SNJ54HCT373W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN54HCT373, SN54HCT373-SP, SN74HCT373 :**

● Catalog: [SN74HCT373](#), [SN54HCT373](#)

● Military: [SN54HCT373](#)

● Space: [SN54HCT373-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application



**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT373DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74HCT373NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74HCT373PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74HCT373PWT	TSSOP	PW	20	250	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT373DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HCT373NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74HCT373PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74HCT373PWT	TSSOP	PW	20	250	367.0	367.0	38.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G20)

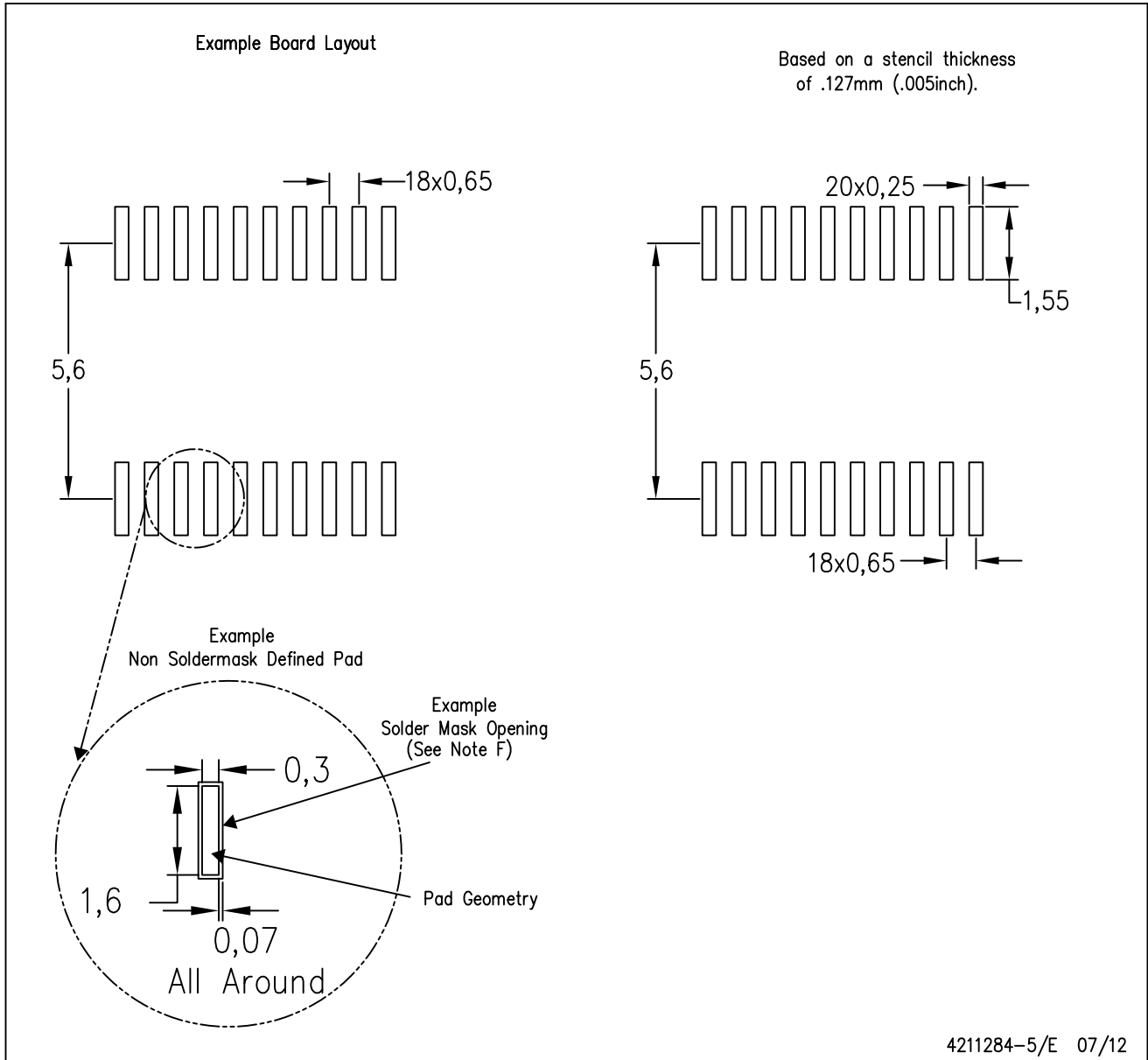
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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